

## REMARKS

Claims 1 and 2 are rejected.

Claim 1 is rejected under 35 U.S.C. § 112.

Claims 1 and 2 are rejected under 35 U.S.C. § 102(b).

Claim 1 is amended. New claims 3-5 are added.

No new matter is added.

Claims 1-5 are now pending in the application.

Applicant requests reconsideration and allowance of the claims in light of the above amendments and following remarks.

***Claim Rejection – 35 U.S.C. § 112***

Claim 1 is rejected under 35 U.S.C. § 112, first paragraph, as based on a disclosure which is not enabling.

The applicant respectfully traverses.

Claim 1 is amended to include the recitation of a metallic layer 115 formed on the back surface of the semiconductor chip 112. Support for the amendment to claim 1 is found in the specification as originally filed, among other places, in FIG. 4 and page 6, lines 10-13.

***Claim Rejection – 35 U.S.C. § 102***

Claims 1 and 2 are rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,650,915 issued to Alfaro et al. ("Alfaro").

The applicant respectfully traverses.

Claim 1 is amended to include the recitation of a metallic layer 115 formed on the back surface of the semiconductor chip 112. Alfaro discloses a chip 24 attached to base 26 of heat spreader 34 by attachment adhesive 50. (FIG. 2; col. 4, lines 65-66)

Alfaro does not, therefore, teach or disclose, "a metallic layer disposed between the semiconductor chip the metallic adhesive," as recited in amended claim 1. Accordingly, Alfaro does not anticipate claim 1.

Accordingly, claim 1, as amended hereby, is allowable over the prior art. Claim 2, dependent therefrom, is also allowable for its dependency and its own merits.

New claims 3-5 have been added. Support for new claim 3 is found in the specification as originally filed on page 6, lines 13-14. Support for new claim 4 is found in

the specification as originally filed on page 7, lines 6-10. Support for new claim 5 is found in the specification as originally filed on 7, lines 27-29.

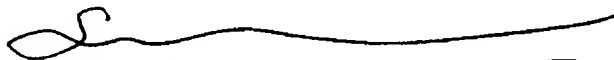
**In conclusion**

For the foregoing reasons, reconsideration and allowance of claims 1-5 of the application as amended is solicited. The Examiner is encouraged to telephone the undersigned at (503) 222-3613 if it appears that an interview would be helpful in advancing the case.

**Customer No. 20575**

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.

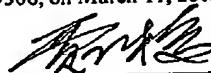


Hosoon Lee

Limited Recognition Under 37 CFR § 10.9(b)

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I hereby certify that this correspondence  
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